

Abstract

Semiconductor device having a semiconductor chip stack on a rewiring plate and production thereof

The invention relates to a semiconductor device (4) having a semiconductor chip stack (1) on a rewiring plate (2). An external contact area (5) having a plurality of external contact area regions (6, 7) which are physically separate from one another is arranged on the underside (3). The individual external contact area regions (6, 7) are assigned to the individual semiconductor chips (10, 11) in the semiconductor chip stack (1), the external contact regions (6, 7) of an individual external contact area (5) having a common external contact (14) which electrically connects the external contact area regions (6, 7).

[Figure 1]